

ABSTRACT

5 A method for fabricating a BGA package is provided. The
method includes the step of providing a substrate having a
first surface with a pattern of conductors thereon, and an
opposing second surface with a die attach area thereon. A
first solder mask is formed on the first surface with via
10 openings to ball bonding pads on the conductors. A second
solder mask is formed on the second surface with an opening
on the die attach area. The opening in the second solder
mask permits a die to be placed through the opening and
adhesively bonded directly to the substrate. The die can
15 then be wire bonded to the conductors and encapsulated in an
encapsulating resin. In addition solder balls can be placed
in the via openings and bonded to the ball bonding pads.